

Chip Scale Review

2017 Editorial Calendar

(Editorial close date: 11/20)

January • February

* indicates show distribution

Industry forecast	<ul style="list-style-type: none"> • SEMI European 3D Summit Grenoble, France (Jan 23-25) * • SMTA Pan Pac Microelectronics Symposium * Kauai, Hawaii (Feb 6-9) • SEMICON Korea Seoul, Korea (Feb 8-10) • APEX Expo San Diego, CA (Feb 14-16) • BiTS Workshop* Mesa, AZ (March 5-8) • IMAPS DPC* Fountain Hills, AZ (March 6-9) • SEMICON China* Shanghai, China (March 14-16)*
Semiconductor merger & consolidation	
Fan-out packaging	
Metrology for advanced packaging applications	
Packaging photonics	
Plasma dicing	
Electronic assembly reliability	
Test & Burn-in	
Testing of MEMS / sensors in HVM	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 6 - Ad Materials Close Jan 11

(Editorial close date: 1/6)

March • April

* indicates show distribution

Wafer bumping	<ul style="list-style-type: none"> • SEMICON SE Asia Penang, Malaysia (Apr 25-27) • ECTC * Lake Buena Vista, FL (May 30- June 2)
3D integration technology for high-density, high performance ICs	
Chip-package Interaction	
Automotive electronic challenges	
Die attach	
Electronic materials	
3D technology failure analysis	
Hi density FO package for RF applications	
Advances in FOWLP	

Ad Space Close Feb 10 - Materials Close Feb 15

(Editorial close date: 3/10)

May • June

* indicates show distribution

Thin wafer handling	<ul style="list-style-type: none"> • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 5-8) • Sensors Expo San Jose, CA (June 27-29) • SEMICON West * San Francisco, CA (July 12-14)
Wafer probing	
Wafer test	
Adhesives, underfill, encapsulants	
Semiconductor mergers	
Lithography solutions for MEMS	
System in package (SiP)	
Advances in thermal management	
Feature: 50 years of CEA-Leti – past, present, future	

Ad Space Close May 19 - Ad Materials Close May 24

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